g		GE Energy	1	Function	nal Testing Spe	ecification		
	Parts & Repa Louisville, K			LOU	-GED-531X170TB	SAGG1		
	Test Procedure for a terminal board							
DOCU	MENT REVISION STATUS	S: Determined by the last of	entry in the "REV" a	nd "DATE" colu	mn			
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DATE 7/18/2	2012	DATE	DATE		DATE 7/18/2012			

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1. SCOPE

1.1 This is a functional testing procedure for a terminal board.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

- **3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
 - **3.1.1** Check board's electronic folder for more information

4. **ENGINEERING REQUIREMENTS**

- 4.1 Equipment Cleaning
 - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
- **4.2** Equipment Inspection
 - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
 - 4.2.1.1 Wires broken, cracked, or loosely connected
 - 4.2.1.2 Terminal strips / connectors broken or cracked
 - 4.2.1.3 Components visually damaged
 - **4.2.1.4** Capacitors bloated or leaking
 - 4.2.1.5 Solder joints damaged or cold
 - 4.2.1.6 Circuit board burned or de-laminated
 - 4.2.1.7 Printed wire runs / Traces burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1		Variac
1		LCR 103

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6. <u>Testing Process</u>

6.1 Setup

- **6.1.1** Placed JP1 in the 2-3 position
- **6.1.2** With an ohmmeter, check for less than 1 ohm between 3TB-71 and 3TB-72 and a open between 3TB-70 and 3TB-71.

6.2 Testing Procedure

- **6.2.1** Apply 24VAC between 3TB-2 and 3TB-26.
- **6.2.2** With an ohmmeter, check for less than 1 ohm between 3TB-71 and 3TB-70 and a open between 3TB-72 and 3TB-71.
- 6.2.3 Remove 24VAC from card.
- **6.2.4** Using capacitance meter, check for .047uf +- 20% between 3TB-75 and COMPL-1.
- 6.2.5 Using a inductance meter, check for 35uh between connector PSPL and 3TB-75
- **6.2.6** Using the schematic diagram verify all point to point connections. Be sure to test SW1 and SW2 in both states.

6.3 ***TEST COMPLETE ***

7. Notes

7.1 None at this time.

8. Attachments

8.1 None at this time.